

EIGHTEENTH ANNUAL

BiTS™

Burn-in & Test Strategies Workshop

March 5 - 8, 2017

Hilton Phoenix / Mesa Hotel
Mesa, Arizona

Archive – Session 8

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Session 8

Hongjun Yao
Session Chair

BiTS Workshop 2017 Schedule

Solutions Day

Wednesday March 8 - 10:30 am

Contact Frequency

" Small Form Factor Cantilever Concepts for High Performance Analog / RF Applications"

Gerhard Gschwendtberger – Cohu

"MRC (MEMS Rubber Contact) Socket Bump Particle Structure & Performance Analysis"

BoHyun Kim, Dave Oh, Justin Yun - TSE Co., Ltd

"Flat Probe Technology For High Frequency Test"

Jason Mroczkowski, Nadia Steckler - Xcerra

Flat Probe Technology for RF Test

Jason Mroczkowski
Nadia Steckler
Xcerra Corporation



BiTS Workshop
March 5 - 8, 2017



Agenda

- RF Application Requirements
- History of Flat probe tech
- Factors that impact Probe RF performance
- RF Design of Flat probe tech
- Radial vs Flat Probe Measurements
- Application Results using Flat Probes
- Future Direction of Flat Probe technology

RF Market Drivers

Demand for instantaneous data transfer is driving high frequency, high bandwidth RF devices

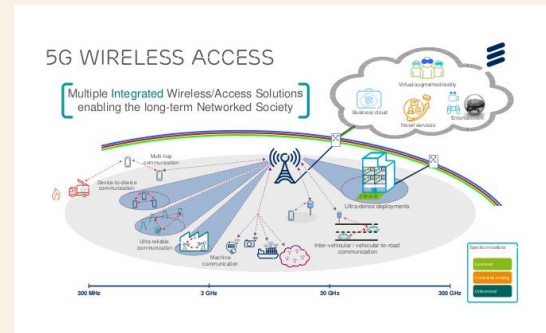
Applications

- WiGig, 5G, Auto Radar, High-Speed Networking

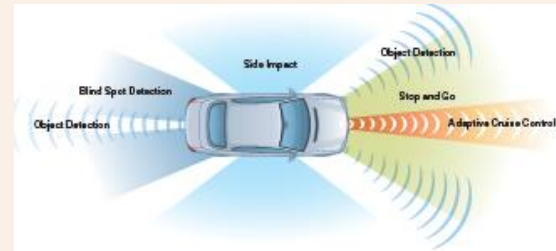
Devices

- RF Transceivers, Power Amplifiers, Low Noise Amplifiers, RF Switches, SERDES, etc.

5G Backhaul



Auto Radar



802.11AD (WiGig)



RF Contact Requirements

- Low loss (>40GHz)
- High isolation (>60dB)
- Low inductance (<0.1nH)
- Matched impedance ($50\Omega \pm 5\%$)
- Low cost of test

BiTS Workshop 2007

- Gemini
- Performance

Challenges With Current Fine Pitch Probe Architectures

- Probe Z Axis Compliance
 - Fine pitches typically dictate the need for low
 - Low spring forces - very fine springs require
 - Higher contact resistance (R_c)
 - Low current carrying capacity (CCC)
 - Low bandwidth, high inductance
 - Some short probe designs exist, but have limitations
 - Probes tend to be very fragile
- Internal Resistance Consistency - Biasing
 - need consistent contact between plunger(s) components throughout compression
- Tip Geometries
 - Limits to DUT tip style, excessive PCB wear loading

BITS 2007

Next-Gen Probe - Cantilever Biased

- 4 piece architecture - barrel-less
- Quad-cantilever arm biased
- Bias force is independent of spring force
- High compliance to test height ratio
- Dual springs - 30g+ force at fine pitch (.4mm)



Gemini™
ECT Patent
Pending

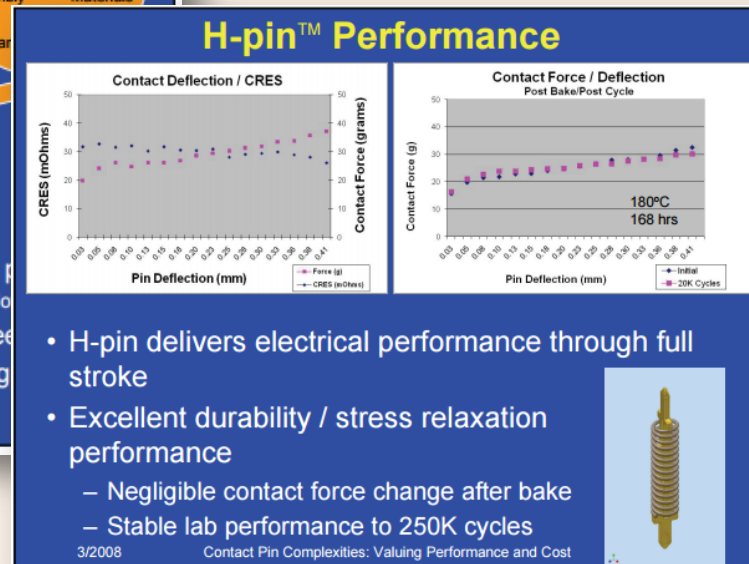
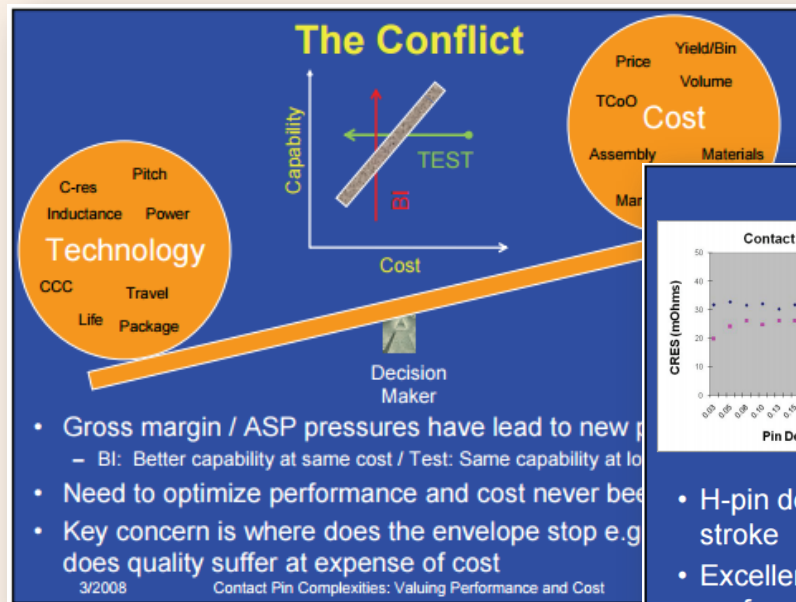
BITS 2007

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BiTS Workshop 2008

- H-Pin

- Performance and Cost



BiTS Workshop 2012

- Stamped Probe
- High Volume

Why Trials on Stamped Spring Probe?

- Easy for mass production and lead time management
- Easy for quality management
- Low cost enabling wider application of
- Finer pitch
- Shorter length for high speed test

03/2012

High Volume Low Cost Stamped Spring Probe Deve

Three Piece Spring Probe Pin by Stamping

- Example 2. Spring probe pin with three bridges



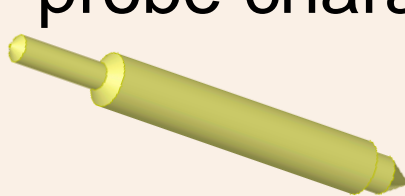
03/2012

High Volume Low Cost Stamped Spring Probe Development

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Flat Probes

- Many Flat probe options available today
- Are they a fad or do they truly add value?
- First lets look at what impacts probe performance
- Then we'll look at specific radial and flat probe characteristics



VS.

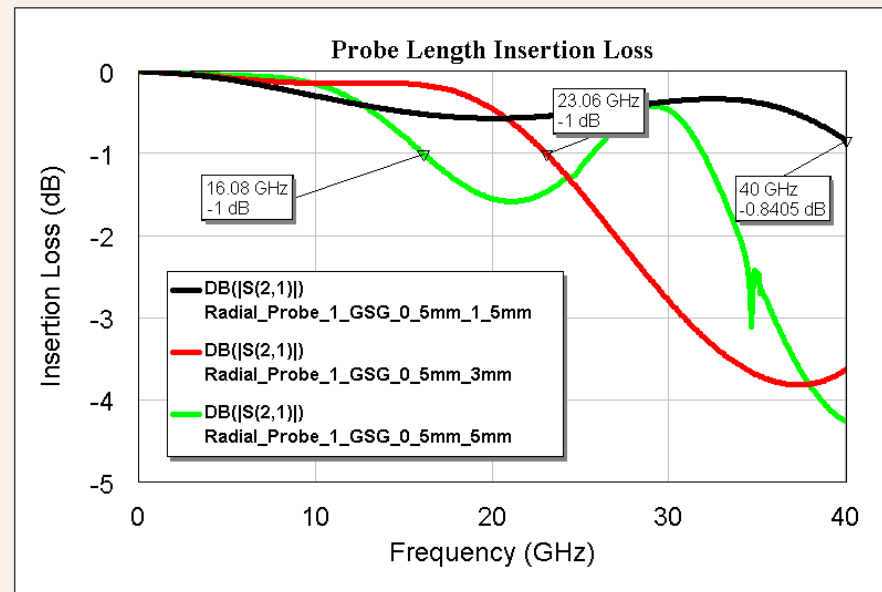
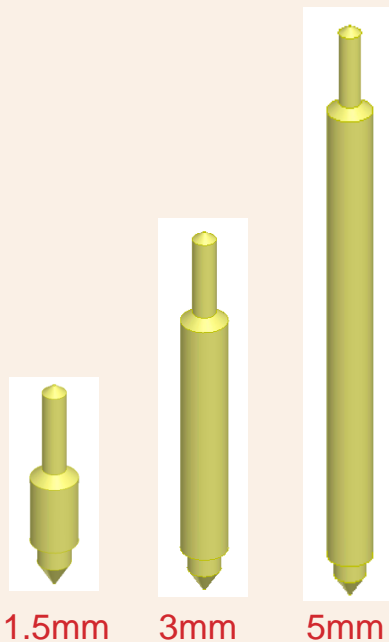


Factors effecting Spring Probe RF Performance

- Length (Major)
- Cross section (Major)
- Material (Minor)
- Tip design (Minor)
- Force (Minor)

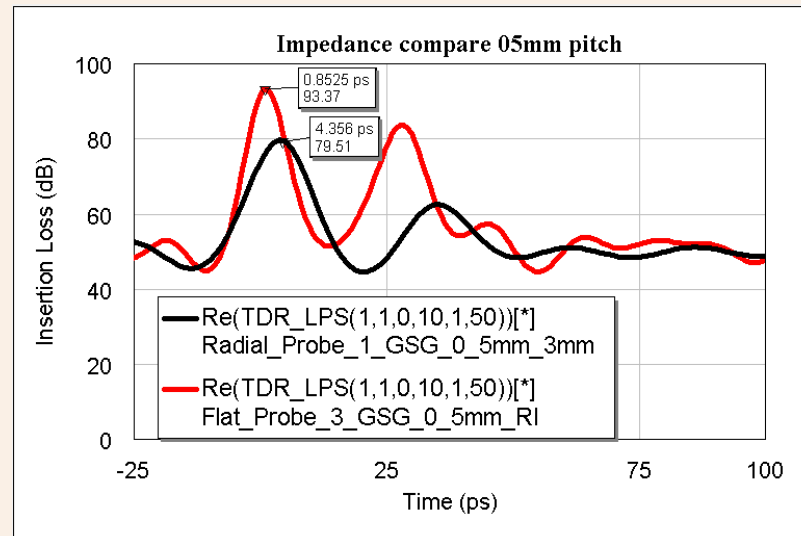
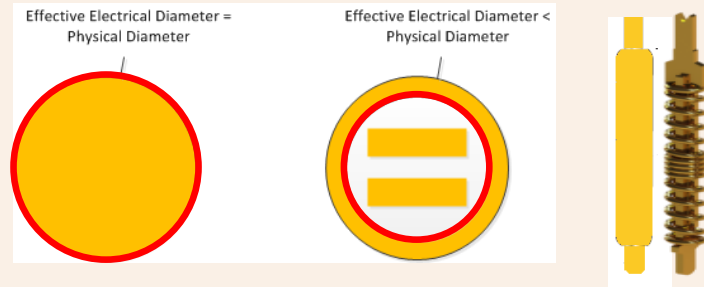
Factors Effecting Probe RF Performance

- Length of probe
 - Inverse relationship to bandwidth



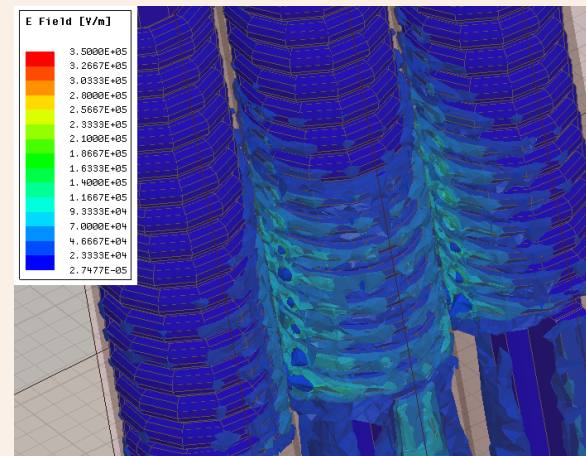
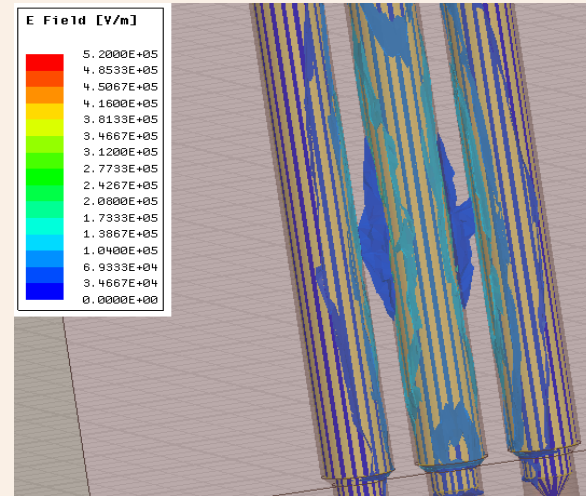
Factors Effecting Probe Performance

- Diameter of probe
 - At native pitches GSG of Radial probes is near 50 Ohms
 - Flat probes have smaller effective diameter than radial probes
 - Flat probes have higher impedance than Radial Probes of the same diameter



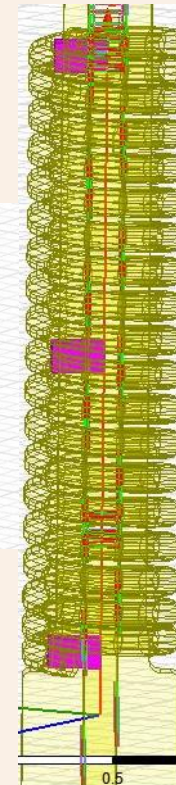
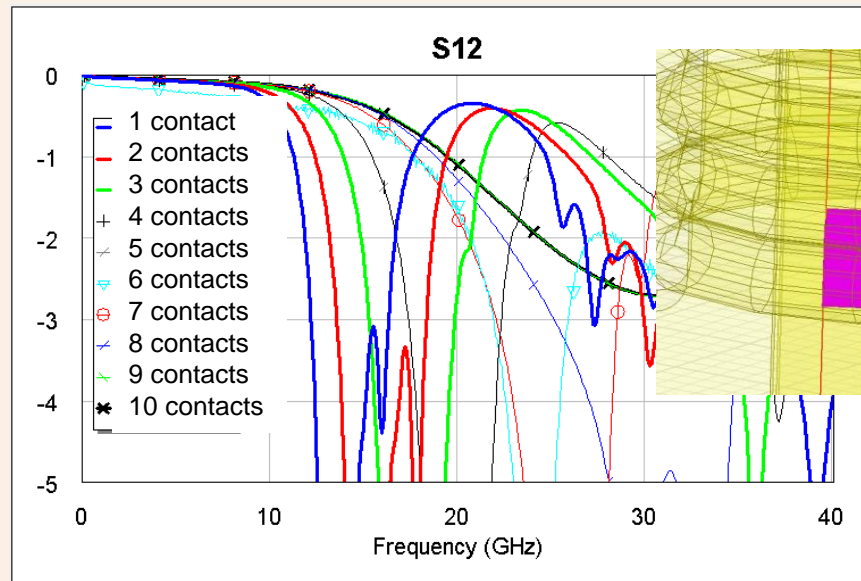
RF Factors - Skin Effect

- Skin effect concentrates current on surface nearest return path
- Radial
 - Round
 - Solid Surface
 - Simple electrical model
- Flat
 - External Spring
 - Complex electrical model
 - Smaller effective diameter



Factors Effecting Flat Probe RF Performance

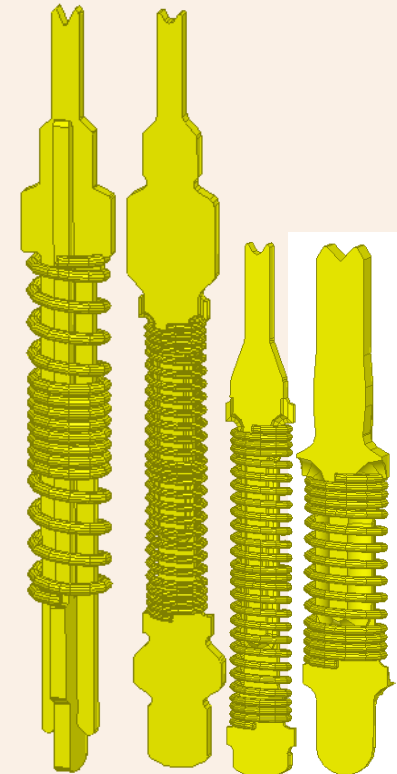
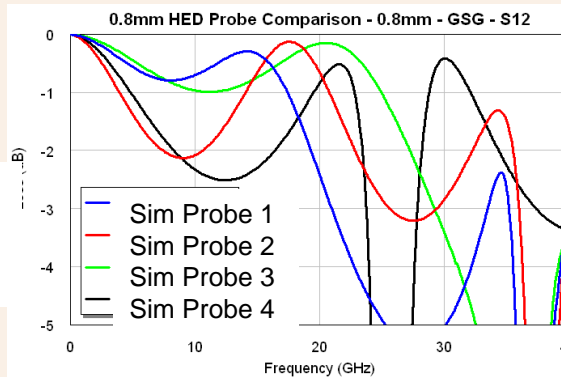
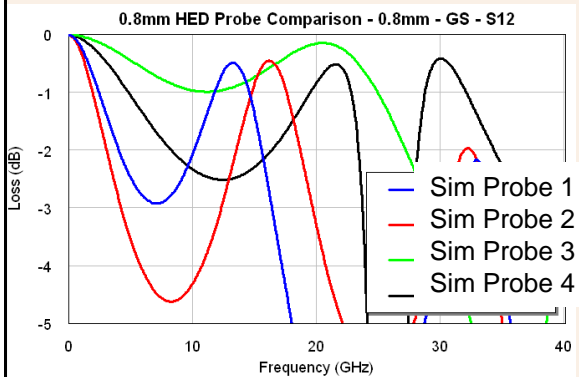
- **Must short the spring** to ensure consistent RF performance
- More windings shorted = better performance
- Minimum 3 contacts required for good RF correlation



Various Flat Probe Simulation Results

- Results show very different performance depending on cross section and length

	Sim Probe 1	Sim Probe 2	Sim Probe 3	Sim Probe 4
S12 GS (-1dB)	2.4 GHz	2.0 GHz	>40 GHz	2.4 GHz
S12 GSG (-1dB)	17.4 GHz	4.2 GHz	25.0 GHz	4.9 GHz



Sim Probe 2 Sim Probe 4
Sim Probe 1 Sim Probe 3

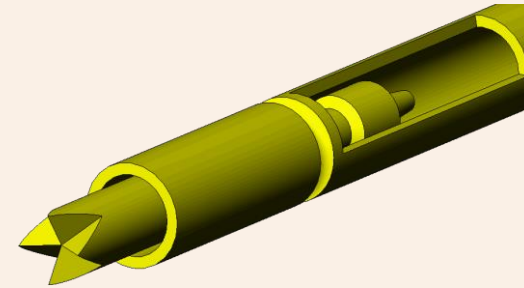
- Flat probe RF performance is impacted by multiple design variables

Factors effecting Contact Resistance Stability

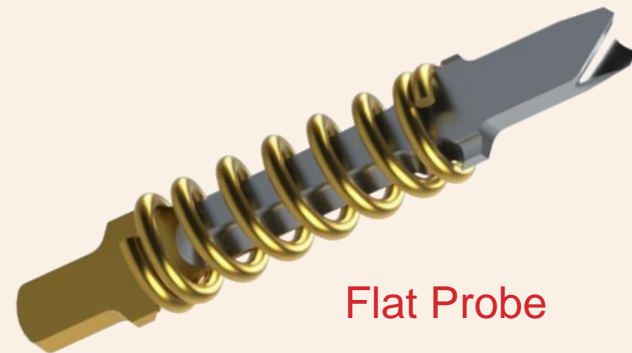
- Length (Minor)
- Cross section (Major)
- Material (Minor)
- Tip design (Major)
- Force (Major)

Factors impacting Contact Resistance

- Radial
 - Internal surfaces require plating specification
 - Make/Break Barrel plating process causes layering
 - Barrel plunger contact 1 or 2 points
- Flat
 - Flat external plating surfaces
 - Large contact surface between top and bottom plungers
 - Improved biasing



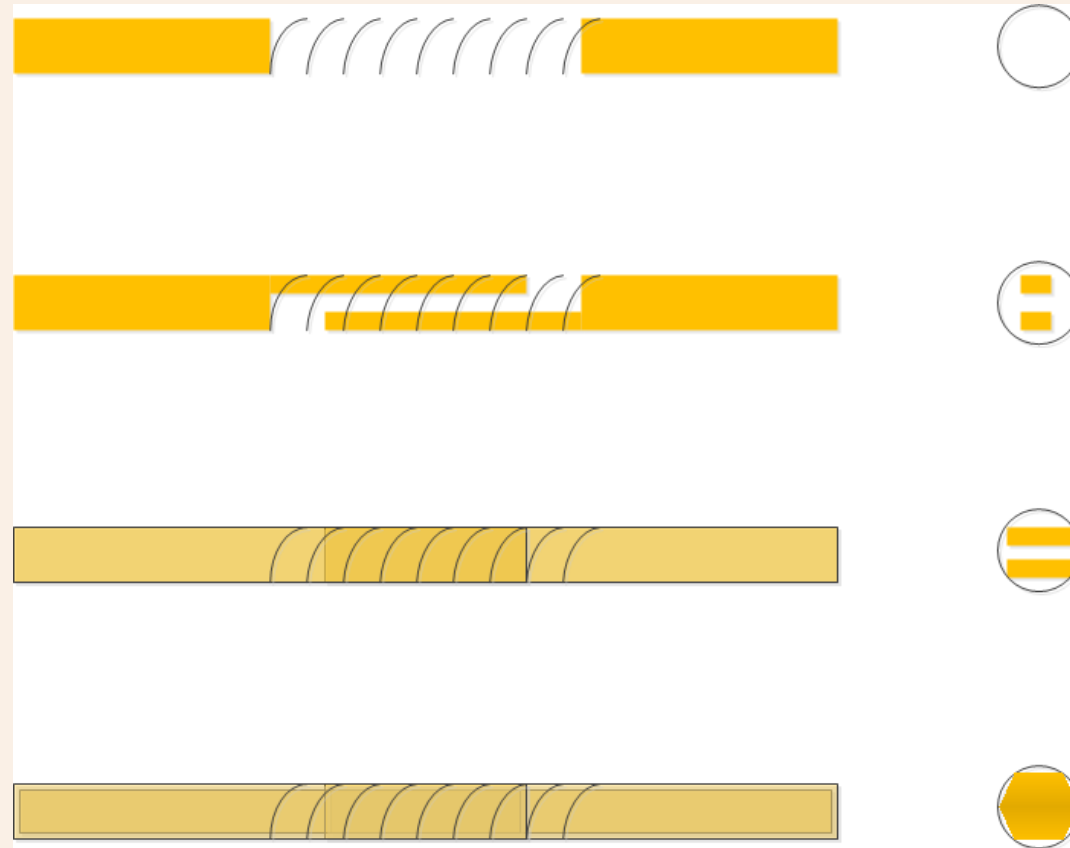
Radial Probe



Flat Probe

Flat Probe Cross-Section Design

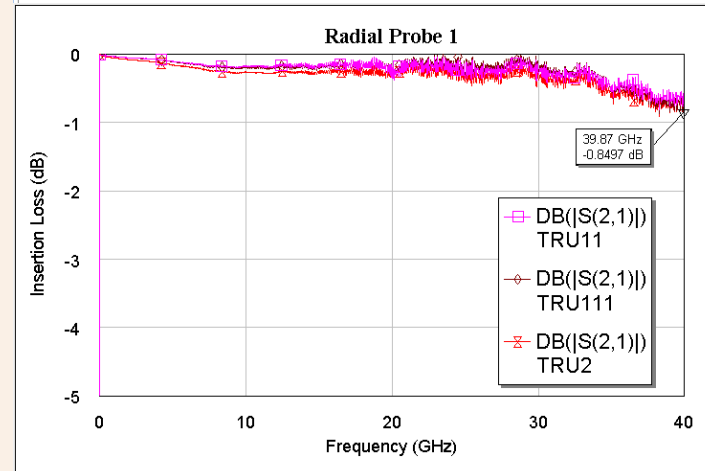
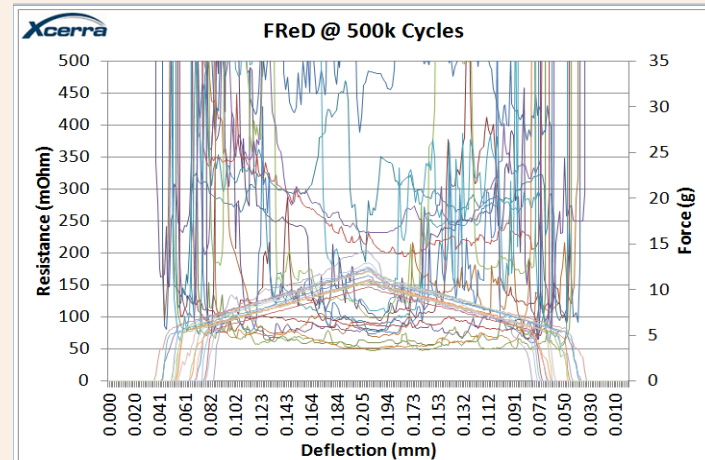
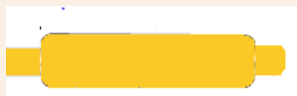
- Worst
- Bad
- Good
- Best



Radial Probe 1

- Short Single ended spring probe
- Consistent high bandwidth
- Low Force
- Contact resistance instability

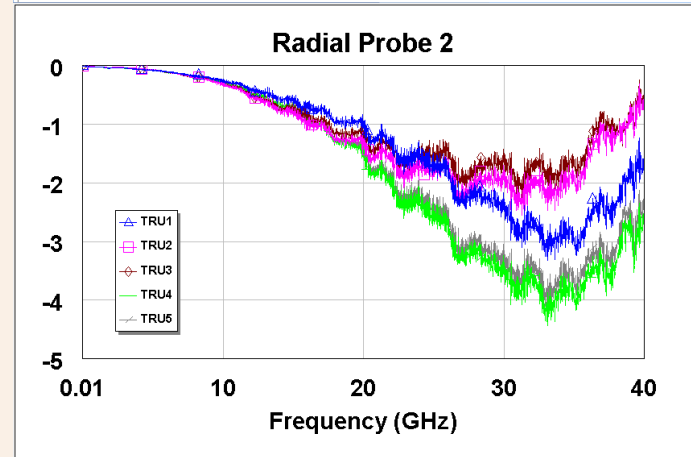
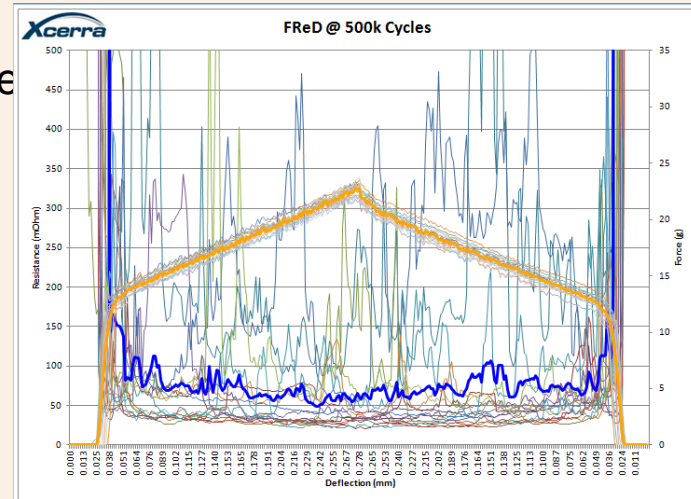
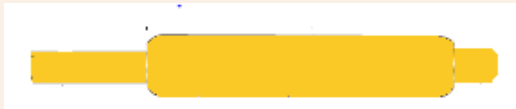
Probe Characteristics	
Pitch	0.5mm
Diameter	0.38mm
Length	1.7mm
Force	15g



Radial Probe 2

- Standard single ended spring probe
- Average length
- Consistent bandwidth to 20GHz
- Contact resistance instability

Probe Characteristics	
Pitch	0.5mm
Diameter	0.3mm
Length	3mm
Force	30g



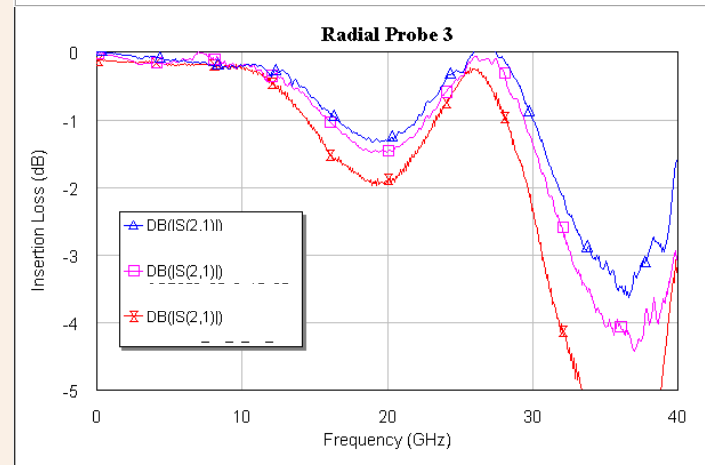
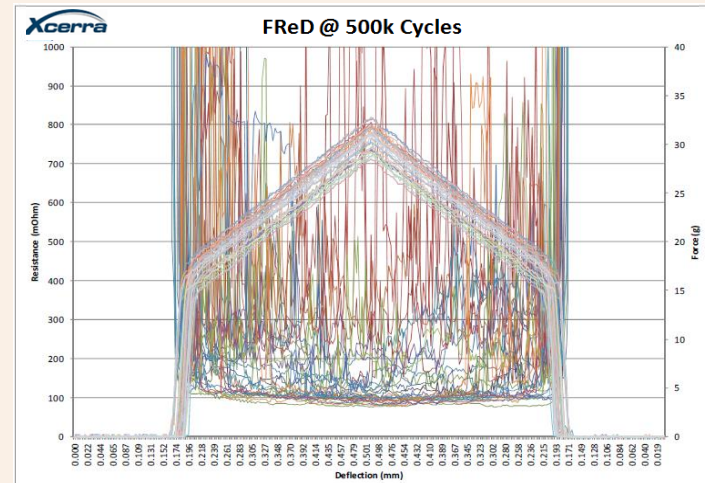
Flat Probe Technology for RF Test

Radial Probe 3

- Long double ended spring probe
- High Impedance mismatch
- 15Ghz Bandwidth
- Contact resistance instability
- No internal bias

Probe Characteristics

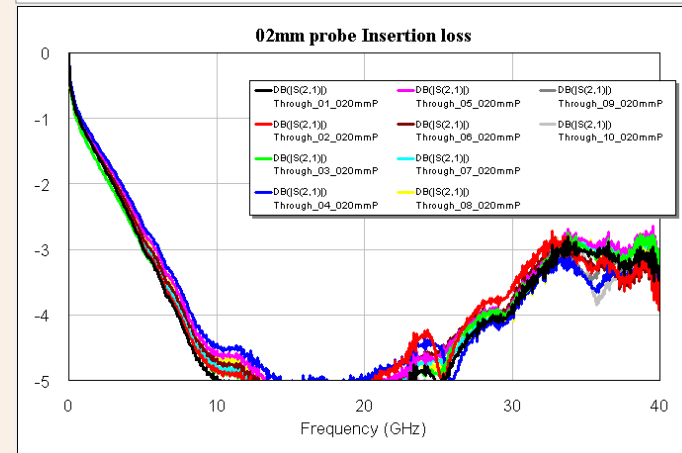
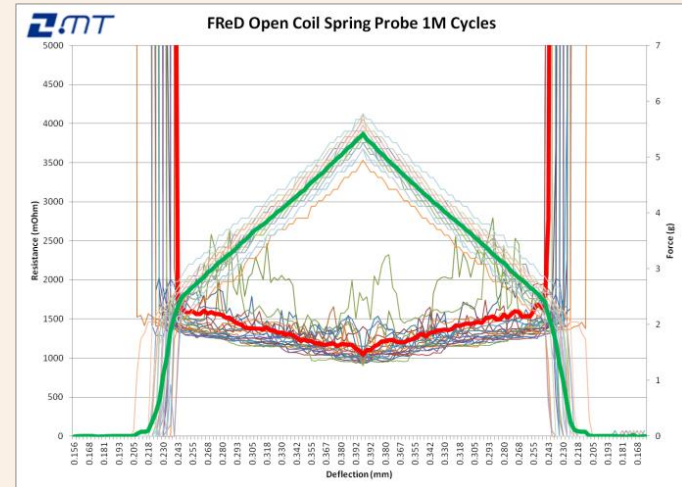
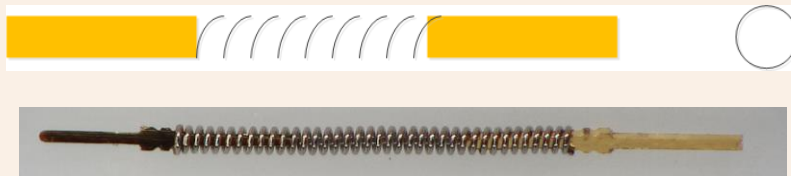
Pitch	0.5mm
Diameter	0.3mm
Length	6mm
Force	32g



Flat Probe 1

- Long Flat Probe for WLCSP applications
- Spring is DC and RF Path
- Poor RF performance of spring inductor

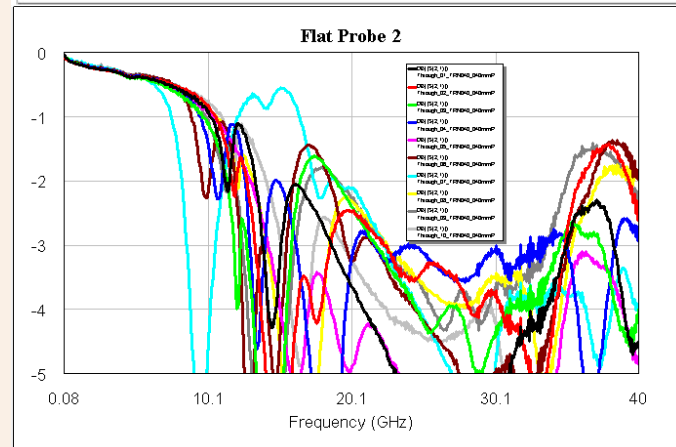
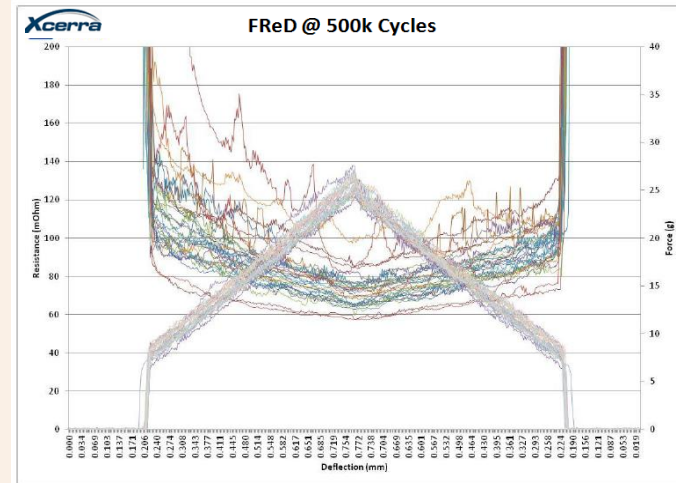
Probe Characteristics	
Pitch	0.2mm
Diameter	0.1mm
Length	7mm
Force	6g



Flat Probe 2

- Standard double ended probe length
- Small Plungers
- Inconsistent spring contact causes resonance above 7GHz

Probe Characteristics	
Pitch	0.4mm
Diameter	0.33mm
Length	5mm
Force	25g

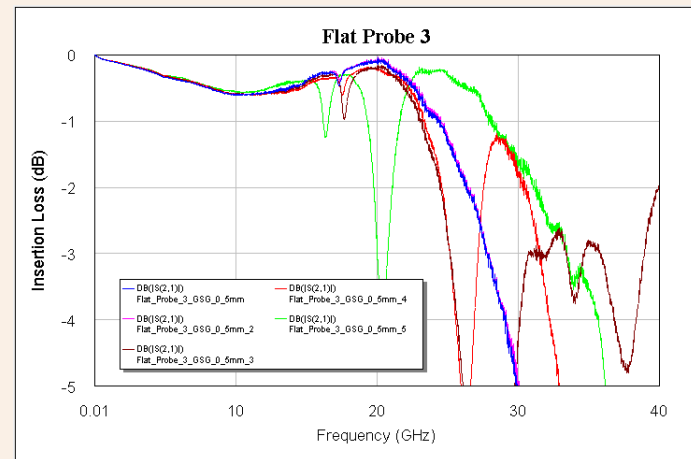
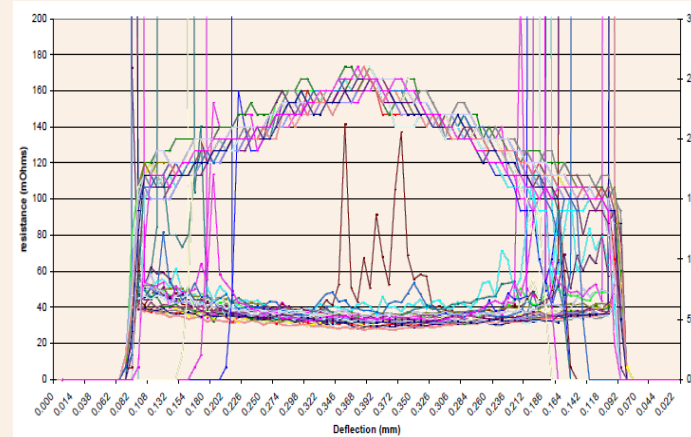


Flat Probe 3

- Standard single ended probe length
- Consistent resistance
- Minor spring resonance @ 17Ghz

Probe Characteristics

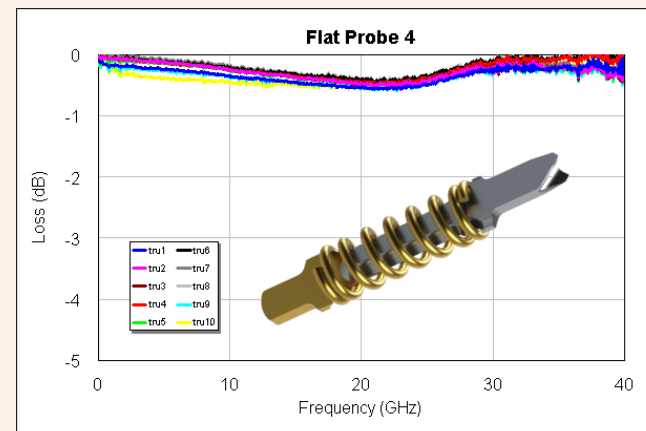
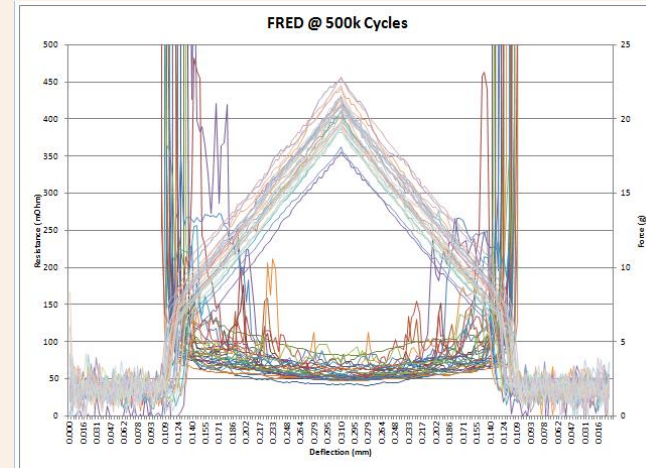
Pitch	0.5mm
Diameter	0.3mm
Length	3mm
Force	25g



Flat Probe 4 - ACE

- Short Probe
- Large Plungers
- Consistent spring contact – no resonances
- Consistent and low resistance

Probe Characteristics	
Pitch	0.4mm
Diameter	0.29mm
Length	1.5mm
Force	17g



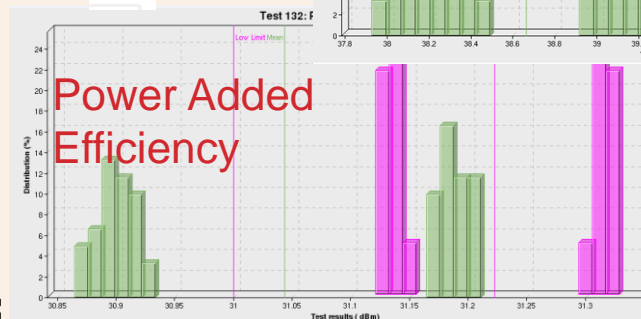
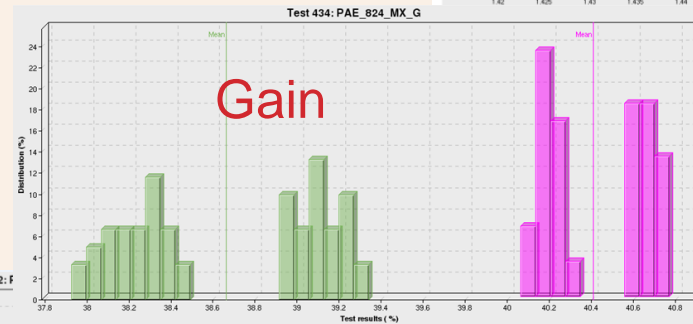
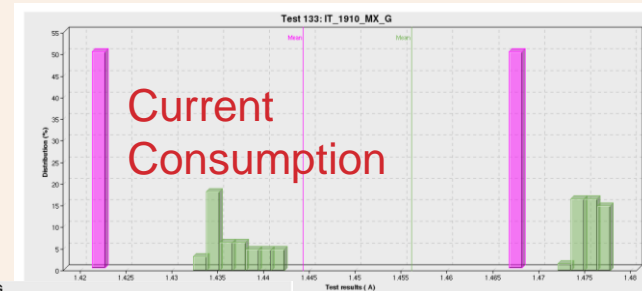
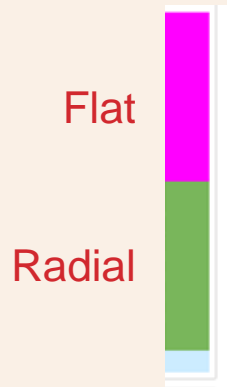
Application Feedback - ACE



Parameters	Units	25.078 Gbps			28.05 Gbps		
		Solder	Socket	Delta	Solder	Socket	Delta
Tr	pS	15.74	17.54	-1.8	15.73	17.39	-1.7
Tf	pS	16.43	16.05	0.4	16.52	16.05	0.5
Jpp	pS	5.762	7.138	-1.4	6.721	7.59	-0.9
EYE Amp	Vpp	802	734.2	68	789	717.8	71
EYE Width	pS	33.6	33.11	0.5	29.95	29.82	0.1

Customer Feedback - ACE

- Flat has Lower Current Consumption
- Flat Standard Deviation is Less
- Flat results in higher Gain
- Flat adds 2% Power Added Efficiency



Flat Performance Wins!

Conclusion

- You can in fact use Flat Probes for RF applications
- Flat Probes offer High Performance and Low Cost of Test
- Flat Probes For RF applications need to be designed and fabricated with care to avoid spring resonances

Flat Probe Roadmap: Atlas, ACE, Nexus

